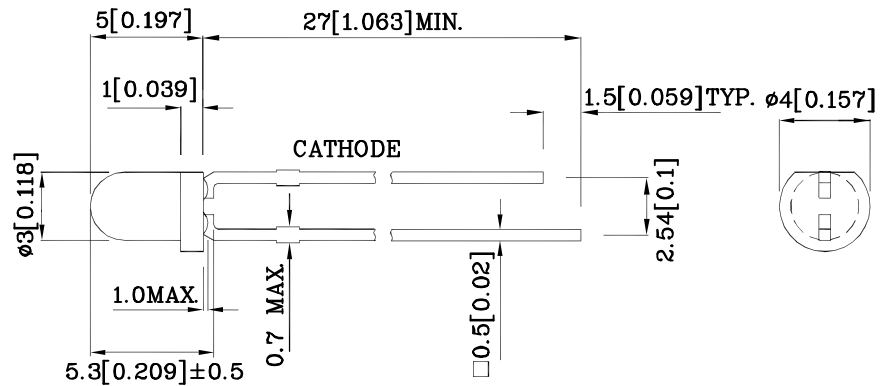


Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



Package Schematics



Notes:

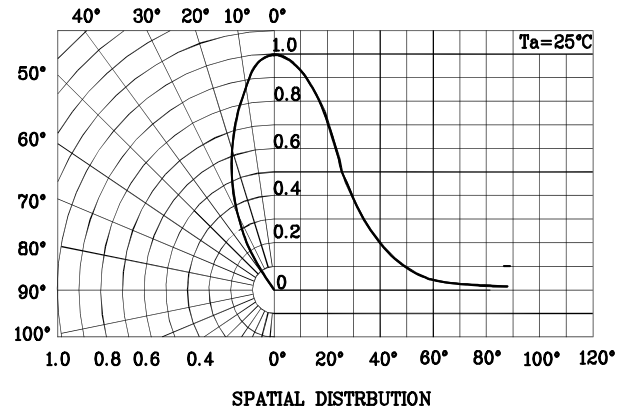
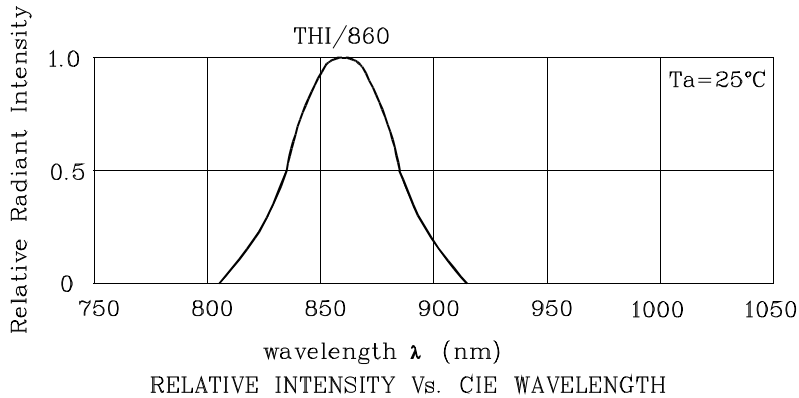
1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 (0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		THI/860 (GaAlAs)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	50	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	1000	mA
Power Dissipation	P _D	80	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

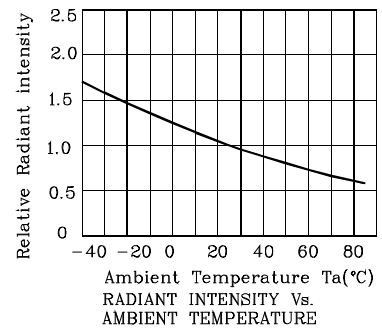
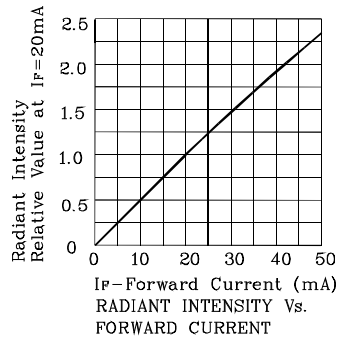
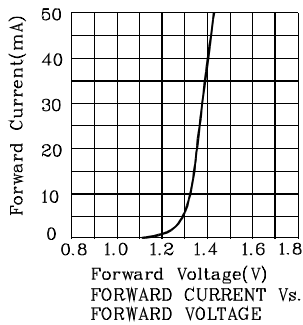
Operating Characteristics ($T_A=25^\circ\text{C}$)		THI/860 (GaAlAs)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	1.35	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	1.6	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission CIE127-2007*(Typ.) ($I_F=20\text{mA}$)	λ_P	860*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	50	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	30	pF

Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* ($P_o=\text{mW/sr}$) @20mA		Radiant Intensity CIE127-2007* ($P_o=\text{mW/sr}$) @50mA		Wavelength CIE127-2007* nm λ_P	Viewing Angle 2 θ 1/2
			min.	typ.	min.	typ.		
XTHI30W860	GaAlAs	Water Clear	8*	16*	15*	50*	860*	50 $^\circ$

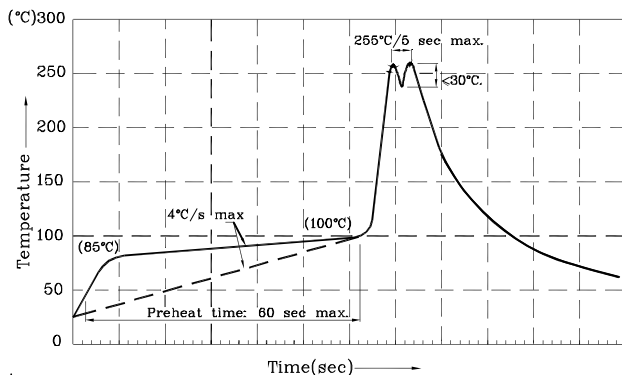
*Radiant Intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ THI/860



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Remarks:

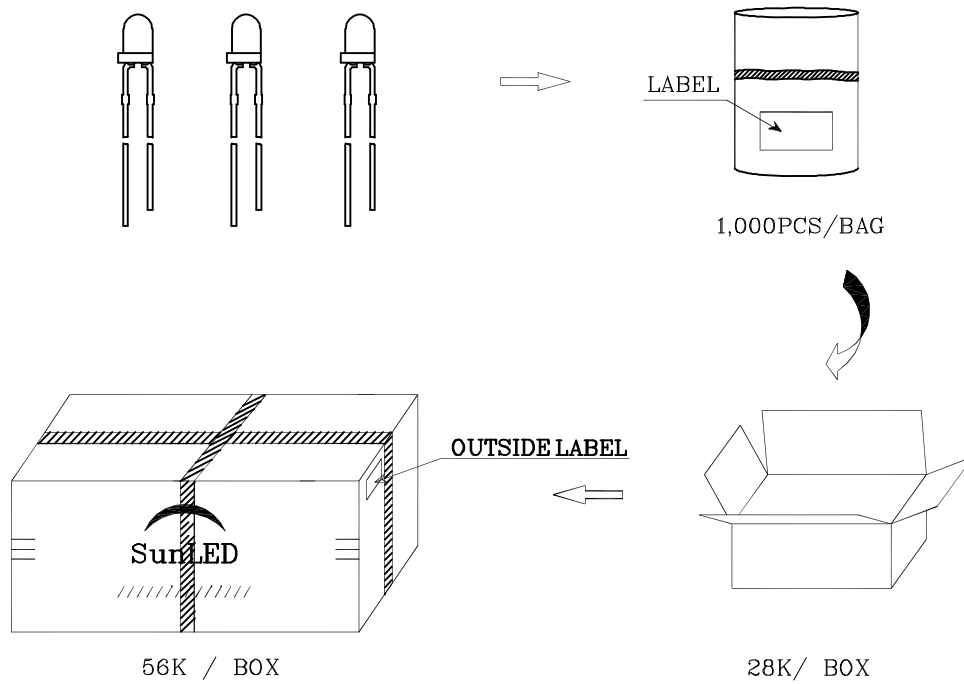
If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux),

the typical accuracy of the sorting process is as follows:

1. Radiant Intensity / Luminous Flux: +/-15%
2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters

PACKING & LABEL SPECIFICATIONS





Q.C. Q C

XX XX XXXX

PASSED

P/NO : Xxxx30x	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO:  XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	